EF7542F-36E　Users Guide

1. General Description

EF7542F-36E is a Flash MCU programming adapter designed for the programmer main unit, EFP-I.

The adapter (EF7542F-36E) installed on the top of the programmer (EFP-I) allows user to program Renesas Technology Corp. 8-bit Flash MCUs, specifically for 7542 Group MCUs.

The adapter is equipped with a 36-pin clamshell socket supporting 36-pin 0.8mm SSOP package (Type No: 36P2R-A).

Fig 1.1 shows the adapter appearance.

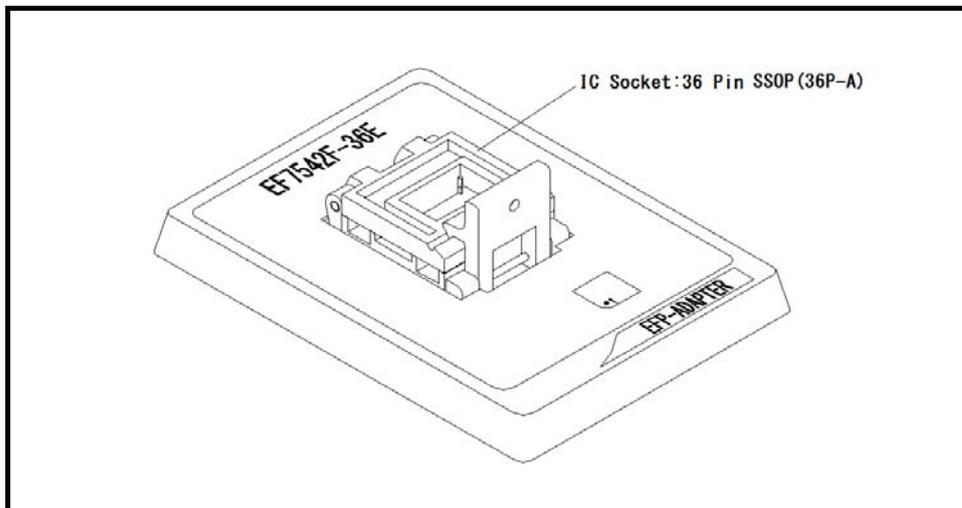\<Packing contents\>

1)　EF7542F-36E

2)　Users guide (this manual)

Fig 1.1　EF7542F-36E External Figure

2. List of Corresponding MCU and corresponding version

2.1 List of Corresponding MCU

Specifications of the EF7542F-36E are listed in Table 3.1.

Table 3.1: EF7542F-36E Specifications

MCU type	Memory type	Corresponding MCU name	Program Memory Area
M37542F8(BOOT)	Flash memory	M37542F8FP	E000h～FFFFh
M37542F8(DATA)			7000h～7FFFh
M37542F8(NORMAL)			8000h～FFFFh

2.2 About Software version(S/W)

The version numbers such as EFP-1 and WinEFP are displayed by [Help]→[About] in the WinEFP window menu. Please download the latest version up data on the following site when the S/W version such as EFP-I used is old.

〈 EFP-I S/W the latest free download site 〉
http://www.suisei.co.jp/download_e/productdata_efp1_e.html

〈 EFP-S2 S/W the latest free download site 〉
http://www.suisei.co.jp/download_e/productdata_s2_e.html

〈 EFP-S2V S/W the latest free download site 〉
http://www.suisei.co.jp/download_e/productdata_s2_e.html

> **Note on Corresponding Versions**
>
> Above corresponding versions might change without notice on account of the future capability improvement, etc. Furthermore in case the upgrade procedure manual is attached when this product is purchased, please refer to that manual as a priority.

3. Insertion Direction of MCU and cleaning of IC socket

3.1 Insertion Direction of MCU

When MCU is inserted, No.1 pin of the IC socket on EF7542F-36E and MCU's No.1 pin should be connected. The wrong insertion would cause a serious breakage of MCU.
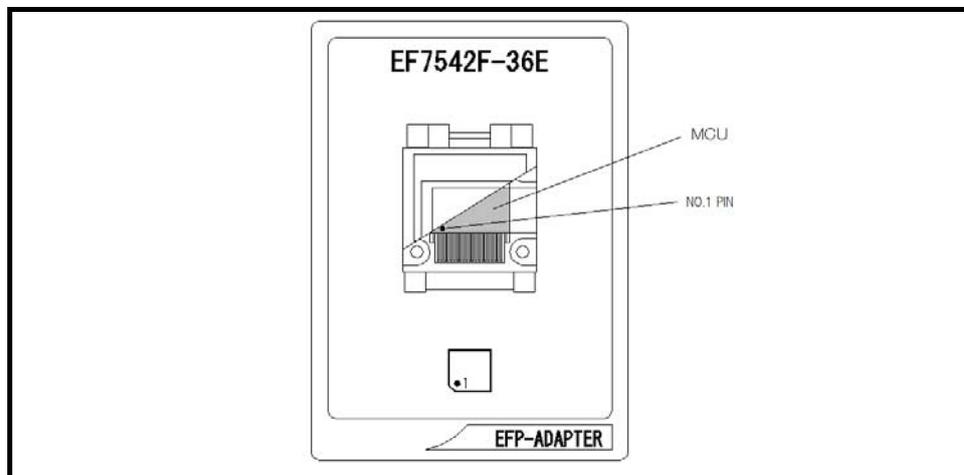
Insertion direction of MCU is shown in Fig.3.1.

Fig 3.1: Pin Orientation of The socket

3.2 Cleaning of IC Socket

A contact pin inside of the IC socket of the MCU unit might deteriorate and a contact failure might occur because of the number of times used and its age of service. As the contact failure may cause incorrect writing of MCU and malfunction of the writer, please take the below measures.

> **Measures against IC Socket Contact Failure**
>
> (i) Please clean the contact pin surface inside of IC socket with a brush, etc. regularly, depending on the number of times used.
> (ii) If the product is not to be used for a long period, please keep it with less humidity in a plastic bag, etc.

Though enquiries on contact failures can be made, we regard IC sockets as consumable supplies. We may recommend you to replace them if a contact failure of IC socket occurs due to its use deterioration.

【Recommended item for cleaning】

About the cleaning of the contact pin in the IC socket, we recommend the use of the nanotech brush (Kita Mfg Co., Ltd).

The nanotech brush can remove the dirt which stuck to a contact pin, a very small amount of metastasis of solder. When a contact poor problem occurred, please try it.

About nanotech brush, please ask us or Kita Mfg Co., Ltd (refer to the following site).

Nanotech brush (Kita Mfg Co., Ltd.) http://www.kita-mfg.com/pro_nanotech_e.html

4. Erase Command

The erase type parameter contained in the erase command enables you to erase by block or erase all blocks. The erase command parameter input dialog is shown in Figure 4.1.

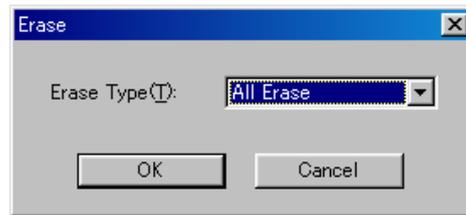＊ This command has not been described in the WinEFP manual.

Fig 4.1: Erase Command Parameter Input Dialog

(1) Erase type

All Erase and block address area (xxxxxxh - xxxxxxh) are displayed in the drop-down list to the right of the erase type parameter display field (displayed by clicking the arrow pointing downward with the mouse). Select the block erase method.

(2) OK button

Execute the block erase command.

(3) Cancel button

Cancel the command.